EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2459	(118/500).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/25 21:02
L2	23	(stack) and (semiconductor near3 wafer) and (substrate near2 detector) and (carrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/25 21:27
L3	152	(stack) and (semiconductor near3 wafer) and (substrate near2 sensor) and (carrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/25 21:02
L4	1	("20010049204").PN.	US-PGPUB	OR	OFF	2006/04/25 21:02
L5	1	("6009890").PN.	US-PGPUB; USPAT	OR	OFF	2006/04/25 21:02
L6	4	"134"/$.ccls. and (substrate near2 inspecting) and (carrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/25 21:02
L7	4	"396"/$.ccls. and (substrate near2 inspecting) and (carrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/25 21:02
L8	14	"118"/$.ccls. and (substrate near2 inspecting) and (carrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/25 21:02
L9	14	("4408560" | "4693777" | "4715392" | "4828878" | "5158616" | "5297568" | "5314509" | "5379784" | "5381808" | "5431179" | "5482068" | "5485644" | "5520744" | "5795405").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/25 21:02
L10	10	("6009890").URPN.	USPAT	OR	ON	2006/04/25 21:02

L11	6	"414"/$.ccls. and (substrate near2 inspecting) and (carrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/25 21:02
L12	3	("5899690" | "5915910" | "6051349"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/25 21:02
L13	10	(stack) and (semiconductor near3 wafer) and (substrate near2 inspecting) and (carrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/25 22:54
L14	11	(("6171403") or ("6517784") or ("6397582") or ("6883305") or ("6761178") or ("6769855") or ("6678081") or ("6811618") or ("6823659") or ("6857838") or ("6841511")).PN.	US-PGPUB; USPAT	OR	OFF	2006/04/25 21:02
L15	166	(134/44).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/25 21:02
L16	237	(118/713).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/25 21:02
L17	399	(414/414).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/25 21:02
L18	487	(134/134).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/25 21:02
L19	541	(134/133).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/25 21:02

L20	714	(134/56R).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/25 21:02
L21	1508	(118/712).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/25 21:02
L22	1	("6051349").PN.	USPAT	OR	OFF	2006/04/25 21:02
L23	2447	(134/902).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/04/25 21:02
L24	1122	carrier with transfer with device with control	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/25 21:02
L25	0	carrier with transfer with device with control and ("118"/$.ccls)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/25 23:04
L26	0	(carrier with transfer with device with control) and ("427"/$.ccls)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/25 21:02
L27	12	(carrier with transfer with device with control) and (semiconductor and coating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/25 21:02
L28	0	(stack) and (count near3 wafer) and (substrate near2 inspecting) and (carrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/25 22:54

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L29	4	(stack) and (number near3 wafer) and (substrate near2 inspecting) and (carrier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/25 22:54
L30	10	carrier with transfer with device with (inspecting or inspect)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/25 23:24
L31	1	wafer and (housed with state) and carrier and (inspection with stage) and (delivery with section)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/25 23:30
L32	1	wafer and (housed with condition) and carrier and (inspection with stage) and (delivery with section)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/25 23:43
L33	0	wafer and (house with condition) and carrier and (inspection with stage) and (delivery with section)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/25 23:30
L34	0	wafer and (house with state) and carrier and (inspection with stage) and (delivery with section)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/25 23:30
L35	1	substrate.clm. and liquid.clm. and process.clm. and carrier.clm. and delivery.clm. and transfer.clm. and stock.clm. and control.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/25 23:44